CLAIMS:

1. An electrical device, having

- an electronic circuit, disposed at least in part on a printed circuit board (3), the circuit having power components (4) each with an arrangement for heat dissipation, and having

- a housing frame (1) for the electronic circuit,

characterized in that

- the housing frame (1) has a number of ribs (6, 7) that are joined to the respective housing frame wall but are offset, and on which the heat-carrying housing parts of the power components (4) are kept in thermal contact; and that

- the housing frame (1) can be joined by thermal contact to a heat-dissipating housing bottom (2).

2. The electrical device of claim 1, characterized in that

- the printed circuit board (3) of the electronic circuit is located on the side of the housing frame (1) opposite the housing bottom (2) of the electromechanical arrangement.

3. The electrical device of claim 1 or 2, characterized in that

- the ribs (6) each protrude by a predetermined amount in to the housing crosswise to the respective housing frame wall.

4. The electrical device of one of claims 1-3, characterized in that

- the ribs (7) each extend parallel to the respective

housing frame wall at a predetermined spacing.

5. The electrical device of one of claims 1-4, characterized in that

- the housing frame (1) can be screwed firmly to the housing bottom (2).

6. The electrical device of one of claims 1-5, characterized in that

- the power components (4) are pressed against the ribs (6, 7) by means of metal clamps (8).

7. The electrical device of one of claims 1-6, characterized in that

- the housing bottom (2) is a component of an electromechanical arrangement and additionally has fins (9) for heat dissipation.